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April 1st, 2010 Renesas Electronics Corporation

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MOS FIELD EFFECT TRANSISTOR μ PA2714GR

SWITCHING P-CHANNEL POWER MOS FET

DESCRIPTION

The μ PA2714GR is P-Channel MOS Field Effect Transistor designed for power management applications of notebook computers and Li-ion battery protection circuit.

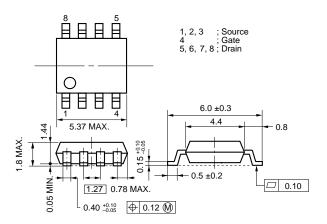
FEATURES

- · Low on-state resistance
 - RDS(on)1 = 20 m Ω MAX. (VGS = -10 V, ID = -3.5 A)
 - RDS(on)2 = 30 m Ω MAX. (Vgs = -4.5 V, ID = -3.5 A)
 - RDS(on)3 = 34 m Ω MAX. (VGS = -4.0 V, ID = -3.5 A)
- Low Ciss: Ciss = 1370 pF TYP.
- Small and surface mount package (Power SOP8)

ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA2714GR	Power SOP8

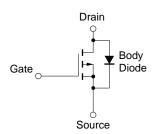
PACKAGE DRAWING (Unit: mm)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C, All terminals are connected.)

ADOCEOTE MAXIMOM HATINGO (TA = 25	o, An ici	illillais ale co	11110010
Drain to Source Voltage (Vgs = 0 V)	$V_{ extsf{DSS}}$	-30	V
Gate to Source Voltage (VDS = 0 V)	Vgss	∓20	V
Drain Current (DC)	$I_{D(DC)}$	∓7	Α
Drain Current (pulse) Note1	ID(pulse)	∓28	Α
Total Power Dissipation Note2	P _{T1}	2	W
Total Power Dissipation Note3	P _{T2}	2	W
Channel Temperature	Tch	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C
Single Avalanche Current Note4	las	-7	Α
Single Avalanche Energy Note4	Eas	4.9	mJ

EQUIVALENT CIRCUIT



- **Notes 1.** PW \leq 10 μ s, Duty Cycle \leq 1%
 - 2. Mounted on a ceramic substrate of 1200 mm² x 2.2 mm
 - 3. Mounted on a glass epoxy board (1 inch x 1 inch x 0.8 mm), PW = 10 sec
 - **4.** Starting T_{ch} = 25°C, V_{DD} = -15 V, R_G = 25 Ω , L = 100 μ H, V_{GS} = -20 \rightarrow 0 V

Remark

Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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ELECTRICAL CHARACTERISTICS (TA = 25°C, All terminals are connected.)

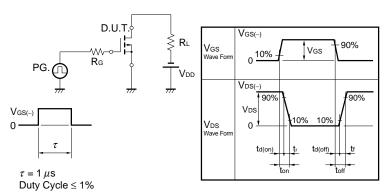
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ioss	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μA
Gate Leakage Current	lgss	$V_{GS} = \mp 20 \text{ V}, V_{DS} = 0 \text{ V}$			∓100	nA
Gate Cut-off Voltage	V _{GS(off)}	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-1.0		-2.5	V
Forward Transfer Admittance	y _{fs}	$V_{DS} = -10 \text{ V}, I_{D} = -3.5 \text{ A}$	5	11		S
Drain to Source On-state Resistance	RDS(on)1	Vgs = -10 V, ID = -3.5 A		16	20	mΩ
	R _{DS(on)2}	Vgs = -4.5 V, ID = -3.5 A		22	30	mΩ
	R _{DS(on)3}	Vgs = -4.0 V, ID = -3.5 A		25	34	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V		1370		pF
Output Capacitance	Coss	Vas = 0 V		390		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		240		pF
Turn-on Delay Time	td(on)	$V_{DD} = -15 \text{ V}, I_D = -3.5 \text{ A}$		8		ns
Rise Time	tr	Vgs = -10 V		15		ns
Turn-off Delay Time	td(off)	R _G = 10 Ω		76		ns
Fall Time	tf			42		ns
Total Gate Charge	Qg	$V_{DD} = -24 \text{ V}$		31		nC
Gate to Source Charge	Qgs	Vgs = -10 V		4		nC
Gate to Drain Charge	Q _{GD}	ID = 7 A	_	9		nC
Body Diode Forward Voltage	V _{F(S-D)}	IF = 7 A, VGS = 0 V		0.82		V
Reverse Recovery Time	trr	IF = 7 A, VGS = 0 V		43		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		27		nC

TEST CIRCUIT 1 AVALANCHE CAPABILITY

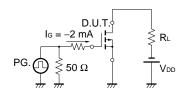
$V_{GS} = -20 \rightarrow 0 \text{ V}$ V_{DS} V_{DS} V_{DS} V_{DS} V_{DS}

-Starting Tch

TEST CIRCUIT 2 SWITCHING TIME



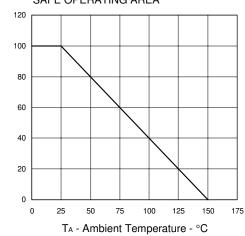
TEST CIRCUIT 3 GATE CHARGE



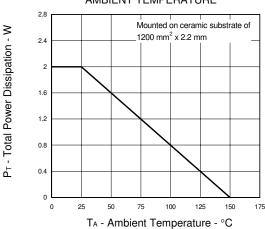
dT - Percentage of Rated Power - %

TYPICAL CHARACTERISTICS (TA = 25°C)

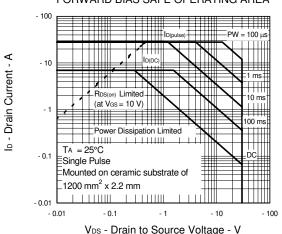
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



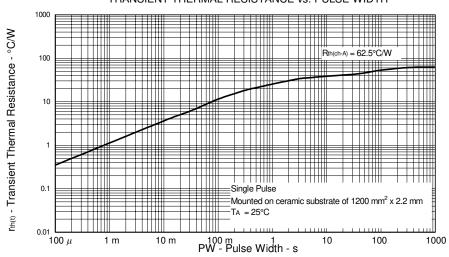
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA



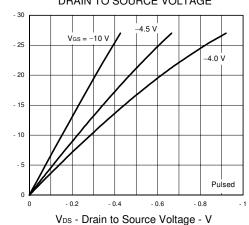
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



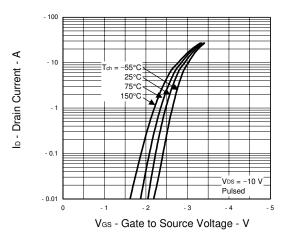
D - Drain Current - A

VGS(off) - Gate Cut-off Voltage - V

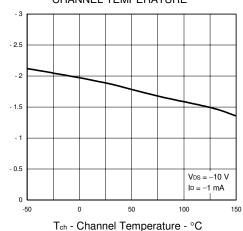
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



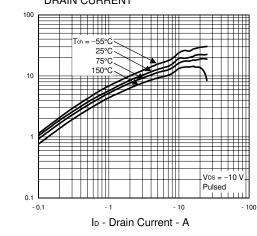
FORWARD TRANSFER CHARACTERISTICS



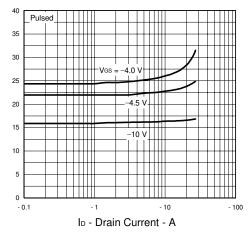
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



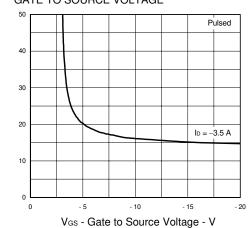
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



R_{DS(o1)} - Drain to Source On-state Resistance - mΩ

RDS(on) - Drain to Source On-state Resistance - mΩ

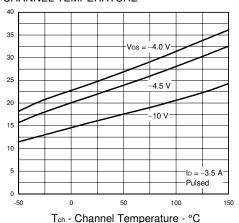
y_{1s} | - Forward Transfer Admittance - S

R_{DS(m)} - Drain to Source On-state Resistance - mΩ

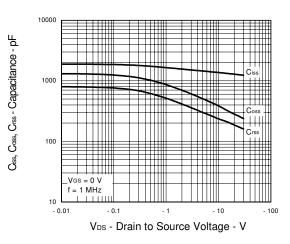
ta(on), tr, ta(off), tr - Switching Time - ns

IF - Diode Forward Current - A

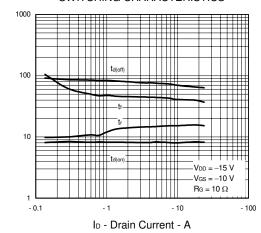
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



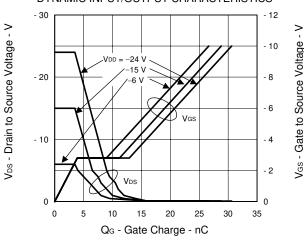
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



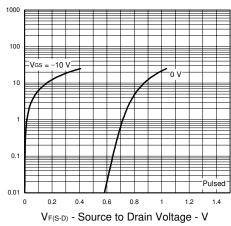
SWITCHING CHARACTERISTICS



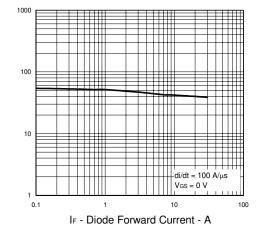
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



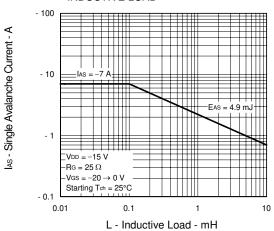
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



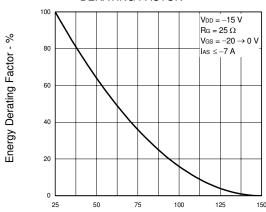
tr - Reverse Recovery Time - ns

μ**PA2714GR**

SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



SINGLE AVALANCHE ENERGY DERATING FACTOR



Starting T_{ch} - Starting Channel Temperature - $^{\circ}C$

NEC μ PA2714GR

[MEMO]

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